

EV Group explore die to wafer bonding and micro LED technologies – August 10, 2022



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DAILY VIDEO



EV Group explore die to wafer bonding and micro LED technologies

Dr Thomas Uhrmann, Business Development Director at the EV Group discusses the heterogeneous integration lab where they have been studying wafer to wafer bonding, hybrid bonding and die to wafer bonding. Dr Uhrmann also discusses some of the challenges with micro LED manufacturing.

[Listen to the full interview.](#)



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